



Bambu Filament

Technical Data Sheet V1.0

PLA Matte

• Basic Info

PLA is the most common material in 3D printing as it's easy to print and inexpensive. Meanwhile, its stiffness and strength can meet most printing needs. It is worth mentioning that it can biodegrade in some artificial composting conditions. **Bambu PLA Matte** is designed for matte surface, and can be printed in speed up to 250 - 300 mm/s, which is faster than regular PLA. It can also make support removal much easier.

• Specifications

Subjects	Data
Diameter	1.75 mm
Net Filament Weight	1 kg
Spool Material	ABS (Temperature resistance 70 °C)
Spool Size	Diameter: 200 mm; Height: 67 mm

• Recommended Printing Settings

Subjects	Data
Drying Settings before Printing	55 °C, 8 hours
Printing and Storage Humidity	< 20% RH (Sealed with desiccant)
Nozzle Temperature	190 - 230 °C
Bed Type	Cool Plate, High Temperature Plate or Texture PEI Plate
Bed Surface Preparation	PVP Glue
Bed Temperature	35 - 45 °C
Cooling Fan	100%
Printing Speed	<300 mm/s
Retraction Length	0.6 - 1.0 mm
Retraction Speed	20 - 40 mm/s
Chamber Temperature	25 - 45 °C
Max Overhang Angle	55°

Subjects	Data
Max Bridging Length	30 mm
Support Material	Support W

• Properties

Bambu Lab has tested the differing aspects in the performance of PLA Matte material, including physical, mechanical, and chemical properties. Typical values are listed as followed:

Physical Properties		
Subjects	Testing Methods	Data
Density	ISO 1183	1.31 g/cm ³
Melt Index	210 °C, 2.16 kg	39.4 ± 0.7 g/10 min
Melting Temperature	DSC, 10 °C/min	163 °C
Glass Transition Temperature	DSC, 10 °C/min	61 °C
Crystallization Temperature	DSC, 10 °C/min	N/A
Vicar Softening Temperature	ISO 306, GB/T 1633	63 °C
Heat Deflection Temperature	ISO 75 1.8 MPa	52 °C
Heat Deflection Temperature	ISO 75 0.45 MPa	58 °C
Saturated Water Absorption Rate	25 °C, 55% RH	0.40%

Mechanical Properties (Dry state)		
Subjects	Testing Methods	Data
Young's Modulus (X-Y)	ISO 527, GB/T 1040	1960 ± 90 MPa
Young's Modulus (Z)	ISO 527, GB/T 1040	1670 ± 110 MPa
Tensile Strength (X-Y)	ISO 527, GB/T 1040	32 ± 3 MPa
Tensile Strength (Z)	ISO 527, GB/T 1040	25 ± 2 MPa
Breaking Elongation Rate (X-Y)	ISO 527, GB/T 1040	32.8 ± 4.3 %
Breaking Elongation Rate (Z)	ISO 527, GB/T 1040	4.8 ± 0.6 %
Bending Modulus (X-Y)	ISO 178, GB/T 9341	2360 ± 250 MPa
Bending Modulus (Z)	ISO 178, GB/T 9341	2040 ± 330 MPa
Bending Strength (X-Y)	ISO 178, GB/T 9341	53 ± 2 MPa
Bending Strength (Z)	ISO 178, GB/T 9341	32 ± 3 MPa
Impact Strength (X-Y)	ISO 179, GB/T 1043	19.2 ± 3.7 kJ/m ² ; 6.3 ± 1.5 (notched)

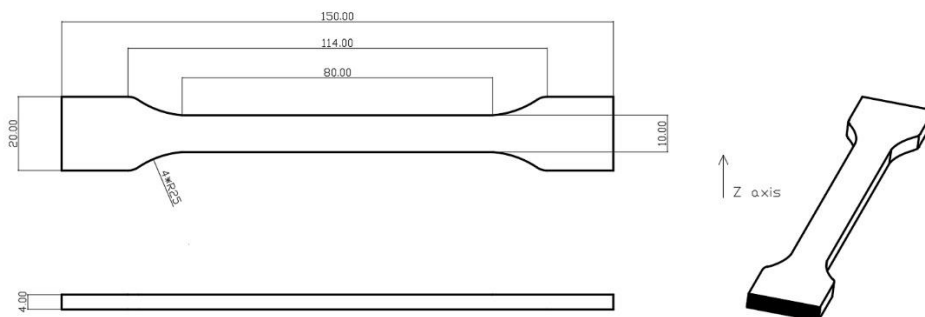
Other Physical and Chemical Properties	
Subjects	Data
Odor	Odorless
Composition	Polylactic acid
Skin Hazards	No hazard
Chemical Stability	Stable under normal storage and handling conditions
Solubility	Insoluble in water
Resistance to Acid	Not resistant
Resistance to Alkali	Not resistant
Resistance to Organic Solvent	Not resistant to some organic solvents
Resistance to Oil and Grease	Resistant to most kinds of oil and grease
Flammability	Flammable and self-extinguishing in the air
Combustion Products	Water, carbon oxides
Odor of Combustion Products	Odorless

- **Specimen Test**

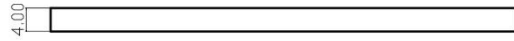
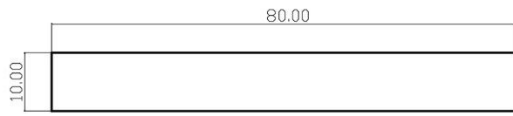
Specimen Printing Conditions	
Subjects	Data
Nozzle Temperature	220 °C
Bed Temperature	35 °C
Printing Speed	200 mm/s
Infill Density	100%

**All the specimens were annealed and dried at 55 °C for 8 hours before testing.*

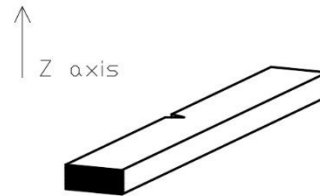
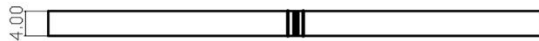
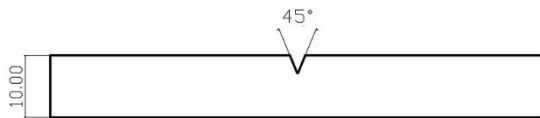
1. Tensile Testing



2. Flexural Testing



3. Impact Testing



- **Disclaimer**

The performance values are tested by standard samples at Bambu Lab, and the values are for design reference and comparison only. Actual 3D printing model performance is related to many other factors, including printers, printing conditions, printing models, printing parameters, etc.

In the process of using Bambu Lab 3D printing filaments, users are responsible for the legality, safety, and performance indicators of printing. Bambu Lab is not responsible for the use of materials and scenarios and is not responsible for any damage that occurs in the process of using our filaments.